

識別碼	任務名稱	工期	開始時間	完成時間	前置任務
1	<b>Hanks Intel overall schedule</b>	<b>150 days</b>	<b>98/4/15</b>	<b>98/11/10</b>	
2					
3	<b>Project Start</b>	<b>0 days</b>	<b>98/4/15</b>	<b>98/4/15</b>	
4					
5	<b>BU+SST - First system build</b>	<b>55 days</b>	<b>98/4/15</b>	<b>98/6/30</b>	
6	<b>Design</b>	<b>24 days</b>	<b>98/4/15</b>	<b>98/5/18</b>	
7	<b>EE</b>	<b>24 days</b>	<b>98/4/15</b>	<b>98/5/18</b>	
8	Circuit entry	2 wks	98/4/15	98/4/28	3
9	Placement and routing	4 wks	98/4/15	98/5/12	3
10	Interference check	4 days	98/5/11	98/5/14	9FS-2 days
11	Gerber out (X00)	2 days	98/5/15	98/5/18	10
12	<b>Build</b>	<b>17 days</b>	<b>98/5/18</b>	<b>98/6/10</b>	
13	PCB fabrication	9 edays	98/5/18	98/5/27	11
14	BOM release	0 days	98/5/23	98/5/23	11FF+5 edays
15	SMT material readiness review	2 days	98/6/1	98/6/2	16SF-1 day
16	UMA Pre-SMT/Discrete Formal SMT build	3 edays	98/6/2	98/6/5	13FF+6 edays
17	SMT UMA Formal build	3 days	98/6/8	98/6/10	16FF+2 days
18	Debug @ QSMC	5 edays	98/6/5	98/6/10	16
19	Ship back PCBA back to QCI	6 edays	98/6/3	98/6/9	16FF+2 edays
20	Sample fabriaction @ QCI	1 day	98/6/9	98/6/9	19
21	<b>Test</b>	<b>18 days</b>	<b>98/6/5</b>	<b>98/6/30</b>	
22	BBU	3 edays	98/6/5	98/6/8	16
23	EA	3 wks	98/6/5	98/6/25	16
24	Compatibility test	3 wks	98/6/10	98/6/30	20
25	Reliability	3 wks	98/6/10	98/6/30	20
26	Thermal	3 wks	98/6/10	98/6/30	20
27	EMC	3 wks	98/6/10	98/6/30	20
28	Antenna	3 wks	98/6/10	98/6/30	20
29					
30	<b>PT - Second system build</b>	<b>51 days</b>	<b>98/6/24</b>	<b>98/9/2</b>	
31	<b>Design</b>	<b>17 days</b>	<b>98/6/24</b>	<b>98/7/16</b>	
32	<b>EE</b>	<b>17 days</b>	<b>98/6/24</b>	<b>98/7/16</b>	
33	Schematics update	4 days	98/6/24	98/6/29	24FS-1 wk
34	Layout modification	1 wk	98/6/30	98/7/6	33
35	Interference check	1 day	98/7/2	98/7/2	34FS-3 days
36	Gerber out (X01)	1 day	98/7/7	98/7/7	34
37	PCB fabrication	9 edays	98/7/7	98/7/16	36
38	<b>Build</b>	<b>33 days</b>	<b>98/7/7</b>	<b>98/8/21</b>	
39	Material Readiness review	1 day	98/7/15	98/7/15	37FF-1 day
40	ICT fixture fabrication	10 edays	98/7/7	98/7/17	36
41	Pre SMT build & Debug	3 days	98/7/17	98/7/21	37
42	ICT fixture debug	3 edays	98/7/21	98/7/24	40,41
43	Formal SMT build & debug	6 days	98/7/24	98/7/31	42FS-1 eday
44	Pre assembly build	1 day	98/7/28	98/7/28	43SS+2 days
45	Fianl assembly readiness review	1 day	98/7/30	98/7/30	44,46SS-2 days
46	Final assembly	3 days	98/8/3	98/8/5	43
47	OBE	3 days	98/8/6	98/8/10	46
48	QRC	3 days	98/8/6	98/8/10	46
49	Ship unit to TDC & CDC	5 days	98/8/17	98/8/21	56
50	Ship units to QCI	4 days	98/8/11	98/8/14	48
51	<b>Test</b>	<b>23 days</b>	<b>98/8/3</b>	<b>98/9/2</b>	
52	PT Phase I	2 wks	98/8/6	98/8/19	46
53	PT Phase II	2 wks	98/8/20	98/9/2	52
54	EA	3 wks	98/8/3	98/8/21	43
55	EMI	3 wks	98/8/4	98/8/24	44FS+4 days
56	Thermal and Acoustic Audit	4 days	98/8/11	98/8/14	47
57	SDA	3 wks	98/8/6	98/8/26	46
58	Function Feedback to ME	0 days	98/8/19	98/8/19	57SS+2 wks
59					
60	<b>ST - 3rd system build</b>	<b>42 days</b>	<b>98/8/19</b>	<b>98/10/16</b>	
61	<b>Design</b>	<b>17 days</b>	<b>98/8/19</b>	<b>98/9/11</b>	
62	<b>EE</b>	<b>17 days</b>	<b>98/8/19</b>	<b>98/9/11</b>	
63	Schematics update and layout modification	14 edays	98/8/19	98/9/2	52
64	1'st Interference check	1 day	98/8/27	98/8/27	63FS-1 wk
65	Final Interference check	1 day	98/9/1	98/9/1	66FS-2 days
66	Gerber out (X02)	0 days	98/9/2	98/9/2	63
67	PCB fabrication	9 edays	98/9/2	98/9/11	66
68	<b>Build</b>	<b>19 days</b>	<b>98/9/11</b>	<b>98/10/7</b>	
69	Material Readiness review	1 day	98/9/11	98/9/11	67FF
70	Pre SMT & SMT build	3 days	98/9/14	98/9/16	67
71	Debug & repair	4 edays	98/9/16	98/9/20	70
72	Fianl assembly readiness review	1 day	98/9/15	98/9/15	73FF-1 day
73	Pre assembly build	0 days	98/9/17	98/9/17	70SS+3 edays
74	Final assembly	3 days	98/9/21	98/9/23	73FS+2 edays
75	OBE	3 days	98/9/24	98/9/28	74
76	QRC	3 days	98/9/24	98/9/28	74
77	Ship Critical units	1 day	98/9/25	98/9/25	74FF+2 days
78	ST Critical units enter WH for QSMC	1 day	98/9/25	98/9/25	74FS+1 day
79	Ship units to ADC & TDC & Region	5 edays	98/10/2	98/10/7	87
80	Ship units to QCI	4 edays	98/9/30	98/10/4	76FS+2 days

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81	<b>Test</b>	<b>22 days</b>	<b>98/9/17</b>	<b>98/10/16</b>	
82	BBU	5 days	98/9/17	98/9/23	70
83	ST test case (in China)	3 wks	98/9/24	98/10/14	74
84	ST test case (in Taiwan)	2 wks	98/9/28	98/10/9	77
85	EA	2 wks	98/9/21	98/10/2	71
86	EMI	2 wks	98/9/28	98/10/9	77
87	Thermal and Acoustic Audit	4 days	98/9/29	98/10/2	75
88	SDA	3 wks	98/9/28	98/10/16	78
89	Function feedback to ME	0 days	98/10/9	98/10/9	88SS+2 wks
90					
91	<b>X-Build - 4th system build</b>	<b>30 days</b>	<b>98/9/30</b>	<b>98/11/10</b>	
92	<b>EE</b>	<b>13 days</b>	<b>98/9/30</b>	<b>98/10/18</b>	
93	Schematics update and layout modification	1 wk	98/9/30	98/10/6	86FS-8 days
94	Gerber out (A00)	0 days	98/10/7	98/10/7	93FS+1 day
95	PCB fabrication	10 edays	98/10/8	98/10/18	94FS+1 day
96	<b>Build</b>	<b>18 days</b>	<b>98/10/16</b>	<b>98/11/10</b>	
97	Material Readiness review	1 day	98/10/16	98/10/16	95FS-1 day
98	PreSMT & SMT	4 days	98/10/19	98/10/22	97
99	Repair	4 days	98/10/23	98/10/28	98
100	Final assembly readiness review	0 days	98/10/27	98/10/27	99FS-2 days
101	Pre assembly build	1 day	98/10/26	98/10/26	99SS+2 edays
102	Final assembly	1 eday	98/10/28	98/10/29	101FS+2 days
103	OBE	3 edays	98/10/29	98/11/1	102
104	QRC	3 edays	98/10/29	98/11/1	102
105	Ship	5 days	98/11/4	98/11/10	103FS+2 days
106					
107	<b>Dell RFD</b>	<b>1 day</b>	<b>98/11/4</b>	<b>98/11/4</b>	<b>105SS</b>

